

HM36-12111R0LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	E CORE	Ferrite Core	Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	1.0400	0.5512
			MnO	1313-13-9		0.2912
			ZnO	1314-13-2		0.1560
			Others	-		0.0416
	I CORE	Ferrite Core	Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	0.5000	0.2650
			MnO	1313-13-9		0.1400
			ZnO	1314-13-2		0.0750
			Others	-		0.0200
2	COIL	Enamelled Copper Wire	Copper (Cu)	7440-50-8	1.4000	1.1200
			Polyester Imide (PEI)	-		0.1680
			Polyamide Imide (PAI)	-		0.1120
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0150	0.0145
			Ag 3.0	7440-21-3		0.0005
			Cu 0.5	7440-50-8		0.0001
4	ADHESIVE	Epoxy	Bisphenol F Epoxy Resin	9003-36-5	0.0100	0.0051
			Latent Hardener	-		0.0005
			Hardener	461-58-5		0.0003
			Modified Epoxy Resin	-		0.0023
			Sb <sub>2</sub> O <sub>3</sub>	1309-64-4		0.0005
			CaCO <sub>3</sub>	471-34-1		0.0010
			Others	-		0.0004
5	MARKING	Ink	2-Butanone	78-93-3	0.0005	0.00027
			Methanol	67-56-1		0.00018
			Propylene Glycol Monomethyl Ether	107-98-2		0.00004
			2-Pyrrolidinone, 1-Methyl	872-50-4		0.00002
		Ink	2-Butanone	78-93-3	0.0005	0.00029
			Methanol	67-56-1		0.00021
6	TAPE	3M #75 Tape	Rubber Thermoset Adhesive	-	0.0010	0.0006
			Polyester Film	-		0.0004
7	SPACER	Nomex Paper	Nylon66	32131-17-2	0.0050	0.0049
			Non-regulated Lubricant & Stabilizer	-		0.0001

Total Weight	2.9710
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HM36-1311R95LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	E CORE	Ferrite Core	Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	1.1680	0.6190
			MnO	1313-13-9		0.3270
			ZnO	1314-13-2		0.1752
			Others	-		0.0467
	I CORE	Ferrite Core	Fe <sub>2</sub> O <sub>3</sub>	1309-37-1	0.6110	0.3238
			MnO	1313-13-9		0.1711
			ZnO	1314-13-2		0.0917
			Others	-		0.0244
2	COIL	Enamelled Copper Wire	Copper (Cu)	7440-50-8	1.2560	1.0048
			Polyester Imide (PEI)	-		0.1507
			Polyamide Imide (PAI)	-		0.1005
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0050	0.00483
			Ag 3.0	7440-21-3		0.00015
			Cu 0.5	7440-50-8		0.00003
4	ADHESIVE	Epoxy	Bisphenol F Epoxy Resin	9003-36-5	0.0050	0.0026
			Latent Hardener	-		0.0003
			Hardener	461-58-5		0.0002
			Modified Epoxy Resin	-		0.0011
			Sb <sub>2</sub> O <sub>3</sub>	1309-64-4		0.0002
			CaCO <sub>3</sub>	471-34-1		0.0005
5	MARKING	Ink	2-Butanone	78-93-3	0.0005	0.00027
			Methanol	67-56-1		0.00018
			Propylene Glycol Monomethyl Ether	107-98-2		0.00004
			2-Pyrrolidinone, 1-Methyl	872-50-4		0.00002
		Ink	2-Butanone	78-93-3	0.0005	0.00029
			Methanol	67-56-1		0.00021
6	TAPE	3M #75 Tape	Rubber Thermoset Adhesive	-	0.0010	0.0006
			Polyester Film	-		0.0004

Total Weight	3.0470
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